

ABSTRACT OF THE DISCLOSURE

A silicon condenser microphone package is disclosed. The silicon condenser microphone package comprises a transducer unit, a substrate, and a cover. The substrate includes an upper surface having a recess formed therein. The transducer unit is attached to the upper surface of the substrate and overlaps at least a portion of the recess wherein a back volume of the transducer unit is formed between the transducer unit and the substrate. The cover is placed over the transducer unit and includes an aperture.

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